What Is Claimed Is

1. An LCD monitor, comprising:

a circuit device, forming plural electrodes on one side thereof;

plural bumps, respectively forming on the electrodes;

a substrate, forming plural pads in accordance with the bumps;

a means of connection, comprising a plurality of conductive particles, conducting the bumps and the pads with the conductive particles bonded between; and

a barrier structure forming on the side of the circuit device, separating the conductive particles.

2. The LCD monitor of Claim 1, wherein the barrier structure is made by an isolating material.

3. The LCD monitor of Claim 2, wherein the pads include plural first pads and second pads, wherein the first pads are input terminals of the LCD monitor, and the second pads are output terminals of the LCD monitor.

4. The LCD monitor of Claim 3, wherein the barrier structure is comprised of a first barrier rib extending along a first direction, whereby forming a partition between the bumps corresponding to the first pads.

5. The LCD monitor of Claim 4, wherein the barrier structure is further comprised of a second barrier rib extending along the first direction, forming a partition between the bumps corresponding to the second pads.

6. The LCD monitor of Claim 5, wherein the barrier rib is further comprised of a third barrier rib extending along a

second direction, forming a partition between the bumps corresponding to the first and the second pads.

SUB A6

7. The LCD monitor of Claim 6, wherein the first and the third barrier ribs are connected, forming an L-shaped structure.

8. The LCD monitor of Claim 6, wherein the first and the third barrier ribs are connected, forming a T-shaped structure.

9. The LCD monitor of Claim 6, wherein the second and the third barrier ribs are connected, whereby forming a L-shape structure.

10. The LCD monitor of Claim 6, wherein the second and the third barrier ribs are connected, forming a T-shaped structure.

11. The LCD monitor of Claim 2, wherein the isolating material is polyimide (PI).

12. The LCD monitor of Claim 2, wherein the connecting means is an anisotropic conductive film.

13. The LCD monitor of Claim 2, wherein the bump is made of one metal selected from the group consisting of Au, Cu, Ni, and Zn.

14. The LCD monitor of Claim 2, wherein the substrate is made by glass.

15. The LCD monitor of Claim 2, wherein the circuit device is an integrated circuit.

16. The LCD monitor of Claim 2, wherein the circuit device is a flexible printed circuit.

SUB A6

17. A semiconductor device, comprising:
an electrode formed on a base surface;
a bump formed on the electrode;
a pad;
a connecting means, comprising a plurality of conductive particles, whereby conducting the bump and the pad with the conductive particles bonded between; and
a barrier rib forming on the base surface, separating the conductive particles.

18. The semiconductor device of Claim 17, wherein the barrier rib is made by an isolating material;
the pad is further comprised of plural first pads and second pads, wherein the first pads are input terminals of a LCD monitor, and the second pads are output terminals of the LCD monitor;
the barrier rib is further comprised of a first barrier rib extending along a first direction, separating the conductive particles between the first pads;
the barrier rib is further comprised of a second barrier rib extending along the first direction, separating the conductive particles between the second pads; and
the barrier rib is further comprised of a third barrier rib extending along a second direction, separating the conductive particles between the first and the second pads.

19. The semiconductor device of Claim 18, wherein the first and the second barrier rib are respectively connected to the third barrier rib, forming an L-shaped structure.

20. The semiconductor device of Claim 18, wherein the first and the second barrier ribs are respectively connected to the third barrier rib, forming a T-shaped structure.

SUB A6

21. The semiconductor device of Claim 18, wherein the isolating material is polyimide;

the connecting means is an anisotropic conductive film; and

the bump is made by one metal selected from the group consisting of AU, Cu, Ni, and Zn.

22. A method for making a semiconductor device, comprising the steps of:

providing a circuit device, wherein the circuit device is formed with plural electrodes on one side thereof;

forming a protective layer on the side of the circuit device with the electrodes exposed;

forming plural bumps on the protective layer in accordance with the electrodes, and conducting the electrodes and the bumps; and

forming plural barrier ribs on the side of the circuit device, thereby separating the bumps.